

20. (Amended) A semiconductor device, comprising:  
a substrate having a main surface and a back surface,  
wherein said back surface has a central area, an  
intermediate area surrounding said central area and a  
peripheral area surrounding said intermediate area;  
a semiconductor chip [formed] disposed on said main  
surface;  
a first bump unit [formed] disposed in said central area  
of said back surface,  
wherein said first bump unit includes a plurality  
of bumps that are disposed a first distance apart from each  
other, and  
wherein said first bump unit radiates heat from  
said semiconductor device; and  
a second bump unit formed in said peripheral area of  
said back surface,  
wherein said second bump unit includes a plurality  
of bumps that are disposed a second distance apart from each  
other, said second distance is greater than said first  
distance, and said second distance is less than a third  
distance between said central area and said peripheral area,  
and  
wherein said second bump unit transmits signals.

Please cancel Claim 21 without prejudice or disclaimer.

22. [Amended] The semiconductor device in accordance with Claim [21] 20, wherein a width of said intermediate area of said back surface is greater than said second distance.

Please cancel Claim 23 without prejudice or disclaimer.

Please insert the following new claims:

--24. The semiconductor device in accordance with Claim 2, wherein said plurality of bumps included in said second bump unit is greater in quantity than said plurality of bumps included in said first bump unit.

25. The semiconductor device in accordance with Claim 24, wherein said plurality of bumps included in said first bump unit and said second bump unit are spherical in shape.--

#### REMARKS

Reconsideration and allowance in view of the foregoing amendments and the following remarks are respectfully requested.